

IN THE CLAIMS:

Please amend Claims 1 and 6 as shown below, and cancel Claims 3 and 4 without prejudice or disclaimer of subject matter. The claims, as currently pending in the application, read as follows:

1. (Currently Amended) A semiconductor laser array comprising:
a chip having a plurality of luminous spots; and
a mount for mounting said chip by means of solder;
wherein, semiconductor lasers of the semiconductor laser array are buried
heterojunction type lasers, and
wherein said chip is soldered to said mount in a fashion of junction down
while said chip projects from a corresponding end facet of said mount with a side of said
chip having said plurality of luminous spots projecting away toward the laser beam
~~emitting side~~ from the corresponding end facet of said mount.

2. (Original) A semiconductor laser array according to claim 1, wherein
said mount is made of silicon.

3. to 4. (Canceled)

5. (Original) A semiconductor laser array according to claim 1, wherein
said plurality of luminous spots are driven independently.

6. (Currently Amended) An optical scanner comprising:

BEST AVAILABLE COPY

a semiconductor laser array, said semiconductor laser array including a chip having a plurality of luminous spots and a mount for mounting said chip by means of solder;

a rotary mirror for deflecting ~~the~~ laser beams emitted from said semiconductor laser array; and

a ~~focussing~~ focusing lens for ~~focussing~~ focusing the laser beams deflected by said rotary mirror onto a surface to be scanned;

wherein, semiconductor lasers of the semiconductor laser array are buried heterojunction type lasers, and

wherein said chip is soldered to said mount in a fashion of junction down and while said chip projects from a corresponding end facet of said mount with a side of said chip having said plurality of luminous spots projecting away ~~toward the laser beam emitting side~~ from the corresponding end facet of said mount.

7. (Original) An optical scanner according to claim 6, wherein said lens is made of a plastic material.

BEST AVAILABLE COPY